



Flexible Photonic Devices and Application

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Message from the Guest Editor

Flexible photonics is an emerging and highly multidisciplinary field, offering attractive prospects for advanced applications in information, energy, medical care, etc. Compared to traditional photonics based on rigid materials and structures, flexible photonics have been used in the development of photonic devices that can be mechanically deformed (e.g., bending, folding, stretching, twisting) without compromising their optical performance, thus enabling new product paradigms such as flexible displays, solar cells, wearable photonic sensors, smart photonic textiles, artificial photonic skin, and conformal photonic systems built on curved surfaces. Besides their intrinsic mechanical compliance, it is also possible to achieve flexible photonic devices with desirable biocompatibility, biodegradability or bioabsorbability through material engineering; these are critical for implantable medical devices. This Special Issue aims to highlight new perspectives and the latest advances in flexible photonics, including materials, structural designs, device fabrications and innovative applications. Topics of interest include but are not limited to the following areas:





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Message from the Editor-in-Chief

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